Product / Package Information	
Package	LCC
Body Size	
Lead Count	20
Terminal Finish	Au

Environmental Information	
RoHS Compliant	Yes
High Temperature Compliant	
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Ceramic Package

Description	Materials	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
					Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Ceramic	Ceramic materials and wares, chemical	66402-68-4	2.92E-01	100.00	913218	57.15	571529
			Subtotal	2.92E-01	100.00	913218	57.15	571529
Precious Metals	Metallization	Tungsten	7440-33-7	2.18E-02	100.00	68272	4.27	42727
			Subtotal	2.18E-02	100.00	68272	4.27	42727
Precious Metals	Nickel Plating	Nickel	7440-02-0	2.36E-03	85.00	7400	0.46	4631
Precious Metals		Cobalt	7440-48-4	4.17E-04	15.00	1306	0.08	817
			Subtotal	2.78E-03	100.00	8706	0.54	5449
Precious Metals	Gold Plating	Gold	7440-57-5	3.13E-03	99.999	9802	0.61	6135
Other inorganic materials		Thallium	7440-28-0	4.70E-07	0.002	1	0.00009	0.92
			Subtotal	3.13E-03	100.00	9804	0.61	6136
Subtotal				**3.19E-01**	100.00	1000000	**62.58**	625841

Combo lid

Description	Materials	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
					Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Kovar	Iron	7439-89-6	7.75E-02	54.00	496800	15.20	151958
Precious Metals		Nickel	7440-02-0	4.16E-02	29.00	266800	8.16	81607
Precious Metals		Cobalt	7440-48-4	2.44E-02	17.00	156400	4.78	47839
			Subtotal	1.44E-01	100.00	920000	28.14	281404
Precious Metals	Lid Frame	Gold	7440-57-5	4.99E-03	80.00	32000	0.98	9788
Precious Metals		Tin	7740-31-5	1.25E-03	20.00	8000	0.24	2447
			Subtotal	6.24E-03	100.00	40000	1.22	12235
Precious Metals	Plating	Nickel	7440-02-0	4.37E-03	70.00	28000	0.86	8564
Precious Metals		Gold	7440-57-5	1.87E-03	30.00	12000	0.37	3670
			Subtotal	6.24E-03	100.00	40000	1.22	12235
Subtotal				**1.56E-01**	100.00	1000000	**30.59**	305874

Bond Wires

Description	Materials	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
					Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Aluminum Wire	Aluminum	7429-90-5	1.00E-03	100.00	1000000	0.196	1960
Subtotal				**1.00E-03**	100.00	1000000	**0.20**	1960

Chip

Description	Materials	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
					Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon Chip	Doped Silicon	7440-21-3	1.90E-02	100.00	1000000	3.72	37240
Subtotal				**1.90E-02**	100.00	1000000	**3.72**	37240

Die Attach

Description	Materials	Substance	CAS#		Homogeneous Material Level		Component Level	
					Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Polyimide-Glass Sphere Mixture	Polyimide Resin	Proprietary	8.90E-03	80.00	5102	1.75	17452
Other inorganic materials		Glass Oxide microsphere	308066-94-6	5.94E-03	20.00	400000	1.16	11634
Subtotal				**1.48E-02**	100.00	405102	**2.91**	29086

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.10E-01**	**100.00**	**1000000**

Control ID: **ADP-F-A-ADR1001AEZ**
Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES
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